

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 06-264035

(43)Date of publication of application : 20.09.1994

(51)Int.Cl. C09J 7/00
C08G 59/40
C08G 73/10
C09J 7/02
C09J 7/02
C09J163/00
// H01L 21/52

(21)Application number : 05-055601

(71)Applicant : HITACHI CHEM CO LTD

(22)Date of filing : 16.03.1993

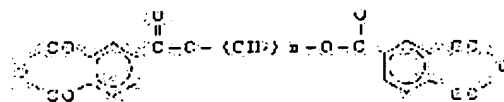
(72)Inventor : TAKEDA SHINJI
YUSA MASAMI
MASUKO TAKASHI
MIYADERA YASUO

(54) ADHESIVE FILM, ITS PRODUCTION, AND METHOD FOR ADHESION

(57)Abstract:

PURPOSE: To prepare an adhesive film for die bonding which, like a conventional silver paste, enables the heat treatment in die bonding to be carried out at a relatively low temp.

CONSTITUTION: This adhesive film contains 100 pts.wt. polyimide resin obtd. by reacting a diamine with a tetracarboxylic dianhydride component contg. at least 70mol% tetracarboxylic dianhydride of the formula (wherein (n) is an integer of 2-20), 1-200 pts.wt. epoxy resin, 0.02-240 pts.wt. phenol resin, 0.0001-100 pts.wt. cure accelerator, and 50-4,000 pts.wt. inorg. filler.



LEGAL STATUS

[Date of request for examination] 22.12.1997

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or

application converted registration]

[Date of final disposal for application]

[Patent number] 2964823

[Date of registration] 13.08.1999

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office